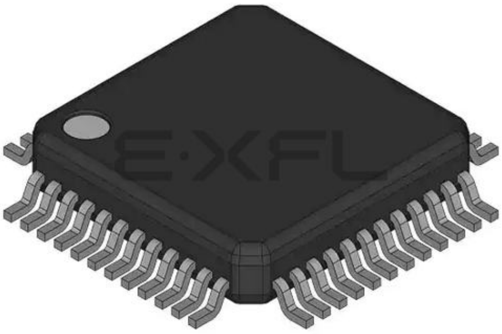

Details	
Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	39
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s08dn32aclf

List of Chapters

Chapter	Title	Page

Table 4-4. Nonvolatile Register Summary

Address	Register Name	Bit 7	6	5	4	3	2	1	Bit 0
0xFFAE	Reserved for storage of FTRIM	0	0	0	0	0	0	0	FTRIM
0xFFAF	Res. for storage of MCGTRM	TRIM							
0xFFB0– 0xFFB7	NVBACKKEY	8-Byte Comparison Key							
0xFFB8– 0xFFBC	Reserved	— —	— —	— —	— —	— —	— —	— —	— —
0xFFBD	NVPROT	EPS		FPS					
0xFFBE	Reserved	—	—	—	—	—	—	—	—
0xFFBF	NVOPT	KEYEN	FNORED	EPGMOD	0	0	0	SEC	

Provided the key enable (KEYEN) bit is 1, the 8-byte comparison key can be used to temporarily disengage memory security. This key mechanism can be accessed only through user code running in secure memory. (A security key cannot be entered directly through background debug commands.) This security key can be disabled completely by programming the KEYEN bit to 0. If the security key is disabled, the only way to disengage security is by mass erasing the Flash if needed (normally through the background debug interface) and verifying that Flash is blank. To avoid returning to secure mode after the next reset, program the security bits (SEC) to the unsecured state (1:0).

6.5.7 Port G Registers

Port G is controlled by the registers listed below.

6.5.7.1 Port G Data Register (PTGD)

	7	6	5	4	3	2	1	0
R	0	0	PTGD5	PTGD4	PTGD3	PTGD2	PTGD1	PTGD0
W	▨	▨						
Reset:	0	0	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 6-42. Port G Data Register (PTGD)

Table 6-40. PTGD Register Field Descriptions

Field	Description
5:0 PTGD[5:0]	**Port G Data Register Bits** — For port G pins that are inputs, reads return the logic level on the pin. For port G pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port G pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTGD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups disabled.

6.5.7.2 Port G Data Direction Register (PTGDD)

	7	6	5	4	3	2	1	0
R	0	0	PTGDD5	PTGDD4	PTGDD3	PTGDD2	PTGDD1	PTGDD0
W	▨	▨						
Reset:	0	0	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 6-43. Port G Data Direction Register (PTGDD)

Table 6-41. PTGDD Register Field Descriptions

Field	Description
5:0 PTGDD[5:0]	**Data Direction for Port G Bits** — These read/write bits control the direction of port G pins and what is read for PTGD reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port G bit n and PTGD reads return the contents of PTGDn.

6.5.7.3 Port G Pull Enable Register (PTGPE)

	7	6	5	4	3	2	1	0
R	0	0	PTGPE5	PTGPE4	PTGPE3	PTGPE2	PTGPE1	PTGPE0
W	▨	▨						
Reset:	0	0	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 6-44. Internal Pull Enable for Port G Register (PTGPE)

Table 6-42. PTGPE Register Field Descriptions

Field	Description
5:0 PTGPE[5:0]	**Internal Pull Enable for Port G Bits** — Each of these control bits determines if the internal pull-up device is enabled for the associated PTG pin. For port G pins that are configured as outputs, these bits have no effect and the internal pull devices are disabled. 0 Internal pull-up device disabled for port G bit n. 1 Internal pull-up device enabled for port G bit n.

NOTE

Pull-down devices only apply when using pin interrupt functions, when corresponding edge select and pin select functions are configured.

6.5.7.4 Port G Slew Rate Enable Register (PTGSE)

	7	6	5	4	3	2	1	0
R	0	0	PTGSE5	PTGSE4	PTGSE3	PTGSE2	PTGSE1	PTGSE0
W	▨	▨						
Reset:	0	0	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 6-45. Slew Rate Enable for Port G Register (PTGSE)

Table 6-43. PTGSE Register Field Descriptions

Field	Description
5:0 PTGSE[5:0]	**Output Slew Rate Enable for Port G Bits** — Each of these control bits determines if the output slew rate control is enabled for the associated PTG pin. For port G pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port G bit n. 1 Output slew rate control enabled for port G bit n.

Note: Slew rate reset default values may differ between engineering samples and final production parts. Always initialize slew rate control to the desired value to ensure correct operation.

Chapter 8
Multi-Purpose Clock Generator (S08MCGV1)

8.1 Introduction

The multi-purpose clock generator (MCG) module provides several clock source choices for the MCU. The module contains a frequency-locked loop (FLL) and a phase-locked loop (PLL) that are controllable by either an internal or an external reference clock. The module can select either of the FLL or PLL clocks, or either of the internal or external reference clocks as a source for the MCU system clock. Whichever clock source is chosen, it is passed through a reduced bus divider which allows a lower output clock frequency to be derived. The MCG also controls an external oscillator (XOSC) for the use of a crystal or resonator as the external reference clock.

All devices in the MC9S08DN60 Series feature the MCG module.

NOTE

Refer to Section 1.3, “System Clock Distribution,” for detailed view of the distribution clock sources throughout the chip.

- LP bit is written to 0

In FLL bypassed internal mode, the MCGOUT clock is derived from the internal reference clock. The FLL clock is controlled by the internal reference clock, and the FLL clock frequency locks to 1024 times the reference frequency, as selected by the RDIV bits. The MCGLCLK is derived from the FLL and the PLL is disabled in a low power state.

8.4.1.4 FLL Bypassed External (FBE)

In FLL bypassed external (FBE) mode, the MCGOUT clock is derived from the external reference clock and the FLL is operational but its output clock is not used. This mode is useful to allow the FLL to acquire its target frequency while the MCGOUT clock is driven from the external reference clock.

The FLL bypassed external mode is entered when all the following conditions occur:

- CLKS bits are written to 10
- IREFS bit is written to 0
- PLLS bit is written to 0
- RDIV bits are written to divide reference clock to be within the range of 31.25 kHz to 39.0625 kHz
- LP bit is written to 0

In FLL bypassed external mode, the MCGOUT clock is derived from the external reference clock. The external reference clock which is enabled can be an external crystal/resonator or it can be another external clock source.The FLL clock is controlled by the external reference clock, and the FLL clock frequency locks to 1024 times the reference frequency, as selected by the RDIV bits. The MCGLCLK is derived from the FLL and the PLL is disabled in a low power state.

NOTE

It is possible to briefly operate in FBE mode with an FLL reference clock frequency that is greater than the specified maximum frequency. This can be necessary in applications that operate in PEE mode using an external crystal with a frequency above 5 MHz. Please see 8.5.2.4, “Example # 4: Moving from FEI to PEE Mode: External Crystal = 8 MHz, Bus Frequency = 8 MHz for a detailed example.

8.4.1.5 PLL Engaged External (PEE)

The PLL engaged external (PEE) mode is entered when all the following conditions occur:

- CLKS bits are written to 00
- IREFS bit is written to 0
- PLLS bit is written to 1
- RDIV bits are written to divide reference clock to be within the range of 1 MHz to 2 MHz

In PLL engaged external mode, the MCGOUT clock is derived from the PLL clock which is controlled by the external reference clock. The external reference clock which is enabled can be an external crystal/resonator or it can be another external clock source The PLL clock frequency locks to a

  - If entering FEE, set RDIV appropriately, clear the IREFS bit to switch to the external reference, and leave the CLKS bits at %00 so that the output of the FLL is selected as the system clock source.
  - If entering FBE, clear the IREFS bit to switch to the external reference and change the CLKS bits to %10 so that the external reference clock is selected as the system clock source. The RDIV bits should also be set appropriately here according to the external reference frequency because although the FLL is bypassed, it is still on in FBE mode.
  - The internal reference can optionally be kept running by setting the IRCLKEN bit. This is useful if the application will switch back and forth between internal and external modes. For minimum power consumption, leave the internal reference disabled while in an external clock mode.
3. After the proper configuration bits have been set, wait for the affected bits in the MCGSC register to be changed appropriately, reflecting that the MCG has moved into the proper mode.
   - If ERCLKEN was set in step 1 or the MCG is in FEE, FBE, PEE, PBE, or BLPE mode, and EREFS was also set in step 1, wait here for the OSCINIT bit to become set indicating that the external clock source has finished its initialization cycles and stabilized. Typical crystal startup times are given in Appendix A, “Electrical Characteristics”.
   - If in FEE mode, check to make sure the IREFST bit is cleared and the LOCK bit is set before moving on.
   - If in FBE mode, check to make sure the IREFST bit is cleared, the LOCK bit is set, and the CLKST bits have changed to %10 indicating the external reference clock has been appropriately selected. Although the FLL is bypassed in FBE mode, it is still on and will lock in FBE mode.

To change from FEI clock mode to FBI clock mode, follow this procedure:

1. Change the CLKS bits to %01 so that the internal reference clock is selected as the system clock source.
2. Wait for the CLKST bits in the MCGSC register to change to %01, indicating that the internal reference clock has been appropriately selected.

8.5.2 MCG Mode Switching

When switching between operational modes of the MCG, certain configuration bits must be changed in order to properly move from one mode to another. Each time any of these bits are changed (PLLS, IREFS, CLKS, or EREFS), the corresponding bits in the MCGSC register (PLLST, IREFST, CLKST, or OSCINIT) must be checked before moving on in the application software.

Additionally, care must be taken to ensure that the reference clock divider (RDIV) is set properly for the mode being switched to. For instance, in PEE mode, if using a 4 MHz crystal, RDIV must be set to %001 (divide-by-2) or %010 (divide -by-4) in order to divide the external reference down to the required frequency between 1 and 2 MHz.

The RDIV and IREFS bits should always be set properly before changing the PLLS bit so that the FLL or PLL clock has an appropriate reference clock frequency to switch to.

8.5.2.3 Example #3: Moving from BLPI to FEE Mode: External Crystal = 4 MHz, Bus Frequency = 16 MHz

In this example, the MCG will move through the proper operational modes from BLPI mode at a 16 kHz bus frequency running off of the internal reference clock (see previous example) to FEE mode using a 4 MHz crystal configured for a 16 MHz bus frequency. First, the code sequence will be described. Then a flowchart will be included which illustrates the sequence.

1. First, BLPI must transition to FBI mode.
   a) MCGC2 = 0x00 (%00000000)
      - LP (bit 3) in MCGSC is 0
   b) Optionally, loop until LOCK (bit 6) in the MCGSC is set, indicating that the FLL has acquired lock. Although the FLL is bypassed in FBI mode, it is still enabled and running.
2. Next, FBI will transition to FEE mode.
   a) MCGC2 = 0x36 (%00110110)
      - RANGE (bit 5) set to 1 because the frequency of 4 MHz is within the high frequency range
      - HGO (bit 4) set to 1 to configure external oscillator for high gain operation
      - EREFS (bit 2) set to 1, because a crystal is being used
      - ERCLKEN (bit 1) set to 1 to ensure the external reference clock is active
   b) Loop until OSCINIT (bit 1) in MCGSC is 1, indicating the crystal selected by the EREFS bit has been initialized.
   c) MCGC1 = 0x38 (%00111000)
      - CLKS (bits 7 and 6) set to %00 in order to select the output of the FLL as system clock source
      - RDIV (bits 5-3) set to %111, or divide-by-128 because 4 MHz / 128 = 31.25 kHz which is in the 31.25 kHz to 39.0625 kHz range required by the FLL
      - IREFS (bit 1) cleared to 0, selecting the external reference clock
   d) Loop until IREFST (bit 4) in MCGSC is 0, indicating the external reference clock is the current source for the reference clock
   e) Optionally, loop until LOCK (bit 6) in the MCGSC is set, indicating that the FLL has reacquired lock.
   f) Loop until CLKST (bits 3 and 2) in MCGSC are %00, indicating that the output of the FLL is selected to feed MCGOUT

Table 10-1. ADC Channel Assignment

ADCH	Channel	Input
00000	AD0	PTA0/ADP0/MCLK
00001	AD1	PTA1/ADP1/ACMP1+
00010	AD2	PTA2/ADP2/ACMP1P-
00011	AD3	PTA3/ADP3/ACMP1O
00100	AD4	PTA4/ADP4
00101	AD5	PTA5/ADP5
00110	AD6	PTA6/ADP6
00111	AD7	PTA7/ADP7
01000	AD8	PTB0/ADP8
01001	AD9	PTB1/ADP9
01010	AD10	PTB2/ADP10
01011	AD11	PTB3/ADP11
01100	AD12	PTB4/ADP12
01101	AD13	PTB5/ADP13
01110	AD14	PTB6/ADP14
01111	AD15	PTB7/ADP15
10000–11001	AD16 through AD25	Reserved
11010	AD26	Temperature Sensor[1]
11011	AD27	Internal Bandgap[2]
11100	Reserved	Reserved
11101	V_{REFH}	V_{REFH}
11110	V_{REFL}	V_{REFL}
11111	Module Disabled	None

Notes:

[1] For information, see Section 10.1.5, “Temperature Sensor”.

10.1.3 Alternate Clock

The ADC module is capable of performing conversions using the MCU bus clock, the bus clock divided by two, the local asynchronous clock (ADACK) within the module, or the alternate clock, ALTCLK. The alternate clock for the MC9S08DN60 Series MCU devices is the external reference clock (MCGERCLK).

The selected clock source must run at a frequency such that the ADC conversion clock (ADCK) runs at a frequency within its specified range (f_{ADCK}) after being divided down from the ALTCLK input as determined by the ADIV bits.

ALTCLK is active while the MCU is in wait mode provided the conditions described above are met. This allows ALTCLK to be used as the conversion clock source for the ADC while the MCU is in wait mode.

ALTCLK cannot be used as the ADC conversion clock source while the MCU is in either stop2 or stop3.

10.1.4 Hardware Trigger

The ADC hardware trigger, ADHWT, is the output from the real time counter (RTC). The RTC counter can be clocked by either MCGERCLK or a nominal 1 kHz clock source.

The period of the RTC is determined by the input clock frequency, the RTCPS bits, and the RTCMOD register. When the ADC hardware trigger is enabled, a conversion is initiated upon an RTC counter overflow.

The RTC can be configured to cause a hardware trigger in MCU run, wait, and stop3.

ADCSC1 = 0x41 (%01000001)

Bit 7	COCO	0	Read-only flag which is set when a conversion completes
Bit 6	AIEN	1	Conversion complete interrupt enabled
Bit 5	ADCO	0	One conversion only (continuous conversions disabled)
Bit 4:0	ADCH	00001	Input channel 1 selected as ADC input channel

ADCRH/L = 0xxx

Holds results of conversion. Read high byte (ADCRH) before low byte (ADCRL) so that conversion data cannot be overwritten with data from the next conversion.

ADCCVH/L = 0xxx

Holds compare value when compare function enabled

APCTL1=0x02

AD1 pin I/O control disabled. All other AD pins remain general purpose I/O pins

APCTL2=0x00

All other AD pins remain general purpose I/O pins

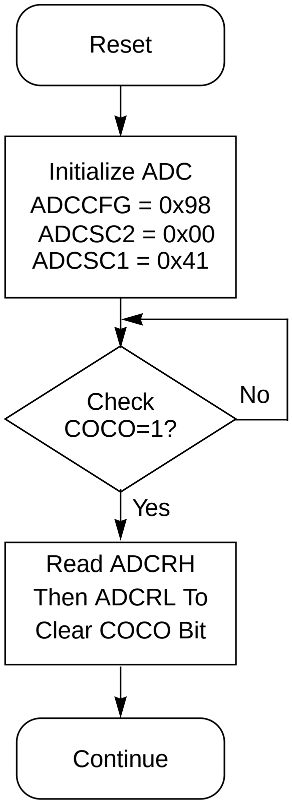

Figure 10-13. Initialization Flowchart for Example

10.6 Application Information

This section contains information for using the ADC module in applications. The ADC has been designed to be integrated into a microcontroller for use in embedded control applications requiring an A/D converter.

10.6.1 External Pins and Routing

The following sections discuss the external pins associated with the ADC module and how they should be used for best results.

10.6.1.1 Analog Supply Pins

The ADC module has analog power and ground supplies (V_{DDAD} and V_{SSAD}) available as separate pins on some devices. V_{SSAD} is shared on the same pin as the MCU digital V_{SS} on some devices. On other devices, V_{SSAD} and V_{DDAD} are shared with the MCU digital supply pins. In these cases, there are separate pads for the analog supplies bonded to the same pin as the corresponding digital supply so that some degree of isolation between the supplies is maintained.

When available on a separate pin, both V_{DDAD} and V_{SSAD} must be connected to the same voltage potential as their corresponding MCU digital supply (V_{DD} and V_{SS}) and must be routed carefully for maximum noise immunity and bypass capacitors placed as near as possible to the package.

If separate power supplies are used for analog and digital power, the ground connection between these supplies must be at the V_{SSAD} pin. This should be the only ground connection between these supplies if possible. The V_{SSAD} pin makes a good single point ground location.

10.6.1.2 Analog Reference Pins

In addition to the analog supplies, the ADC module has connections for two reference voltage inputs. The high reference is V_{REFH}, which may be shared on the same pin as V_{DDAD} on some devices. The low reference is V_{REFL}, which may be shared on the same pin as V_{SSAD} on some devices.

When available on a separate pin, V_{REFH} may be connected to the same potential as V_{DDAD}, or may be driven by an external source between the minimum V_{DDAD} spec and the V_{DDAD} potential (V_{REFH} must never exceed V_{DDAD}). When available on a separate pin, V_{REFL} must be connected to the same voltage potential as V_{SSAD}. V_{REFH} and V_{REFL} must be routed carefully for maximum noise immunity and bypass capacitors placed as near as possible to the package.

AC current in the form of current spikes required to supply charge to the capacitor array at each successive approximation step is drawn through the V_{REFH} and V_{REFL} loop. The best external component to meet this current demand is a 0.1 μF capacitor with good high frequency characteristics. This capacitor is connected between V_{REFH} and V_{REFL} and must be placed as near as possible to the package pins. Resistance in the path is not recommended because the current causes a voltage drop that could result in conversion errors. Inductance in this path must be minimum (parasitic only).

10.6.1.3 Analog Input Pins

The external analog inputs are typically shared with digital I/O pins on MCU devices. The pin I/O control is disabled by setting the appropriate control bit in one of the pin control registers. Conversions can be performed on inputs without the associated pin control register bit set. It is recommended that the pin control register bit always be set when using a pin as an analog input. This avoids problems with contention because the output buffer is in its high impedance state and the pullup is disabled. Also, the input buffer draws DC current when its input is not at V_{DD} or V_{SS}. Setting the pin control register bits for all pins used as analog inputs should be done to achieve lowest operating current.

Empirical data shows that capacitors on the analog inputs improve performance in the presence of noise or when the source impedance is high. Use of 0.01 μF capacitors with good high-frequency characteristics is sufficient. These capacitors are not necessary in all cases, but when used they must be placed as near as possible to the package pins and be referenced to V_{SSA}.

For proper conversion, the input voltage must fall between V_{REFH} and V_{REFL}. If the input is equal to or exceeds V_{REFH}, the converter circuit converts the signal to 0xFFF (full scale 12-bit representation), 0x3FF (full scale 10-bit representation) or 0xFF (full scale 8-bit representation). If the input is equal to or less than V_{REFL}, the converter circuit converts it to 0x000. Input voltages between V_{REFH} and V_{REFL} are straight-line linear conversions. There is a brief current associated with V_{REFL} when the sampling capacitor is charging. The input is sampled for 3.5 cycles of the ADCK source when ADLSMP is low, or 23.5 cycles when ADLSMP is high.

For minimal loss of accuracy due to current injection, pins adjacent to the analog input pins should not be transitioning during conversions.

10.6.2 Sources of Error

Several sources of error exist for A/D conversions. These are discussed in the following sections.

10.6.2.1 Sampling Error

For proper conversions, the input must be sampled long enough to achieve the proper accuracy. Given the maximum input resistance of approximately 7kΩ and input capacitance of approximately 5.5 pF, sampling to within 1/4LSB (at 12-bit resolution) can be achieved within the minimum sample window (3.5 cycles @ 8 MHz maximum ADCK frequency) provided the resistance of the external analog source (R_{AS}) is kept below 2 kΩ.

Higher source resistances or higher-accuracy sampling is possible by setting ADLSMP (to increase the sample window to 23.5 cycles) or decreasing ADCK frequency to increase sample time.

10.6.2.2 Pin Leakage Error

Leakage on the I/O pins can cause conversion error if the external analog source resistance (R_{AS}) is high. If this error cannot be tolerated by the application, keep R_{AS} lower than V_{DDAD} / $(2^N{*}I_{LEAK})$ for less than 1/4LSB leakage error (N = 8 in 8-bit, 10 in 10-bit or 12 in 12-bit mode).

Table 13-3. SCI1C1 Field Descriptions (continued)

Field	Description
3 WAKE	**Receiver Wakeup Method Select** — Refer to Section 13.3.3.2, “Receiver Wakeup Operation” for more information. 0 Idle-line wakeup. 1 Address-mark wakeup.
2 ILT	**Idle Line Type Select** — Setting this bit to 1 ensures that the stop bit and logic 1 bits at the end of a character do not count toward the 10 or 11 bit times of logic high level needed by the idle line detection logic. Refer to Section 13.3.3.2.1, “Idle-Line Wakeup” for more information. 0 Idle character bit count starts after start bit. 1 Idle character bit count starts after stop bit.
1 PE	**Parity Enable** — Enables hardware parity generation and checking. When parity is enabled, the most significant bit (MSB) of the data character (eighth or ninth data bit) is treated as the parity bit. 0 No hardware parity generation or checking. 1 Parity enabled.
0 PT	**Parity Type** — Provided parity is enabled (PE = 1), this bit selects even or odd parity. Odd parity means the total number of 1s in the data character, including the parity bit, is odd. Even parity means the total number of 1s in the data character, including the parity bit, is even. 0 Even parity. 1 Odd parity.

13.2.3 SCI Control Register 2 (SCI1C2)

This register can be read or written at any time.

	7	6	5	4	3	2	1	0
R W	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
Reset	0	0	0	0	0	0	0	0

Figure 13-7. SCI Control Register 2 (SCI1C2)

Table 13-4. SCI1C2 Field Descriptions

Field	Description
7 TIE	**Transmit Interrupt Enable (for TDRE)** 0 Hardware interrupts from TDRE disabled (use polling). 1 Hardware interrupt requested when TDRE flag is 1.
6 TCIE	**Transmission Complete Interrupt Enable (for TC)** 0 Hardware interrupts from TC disabled (use polling). 1 Hardware interrupt requested when TC flag is 1.
5 RIE	**Receiver Interrupt Enable (for RDRF)** 0 Hardware interrupts from RDRF disabled (use polling). 1 Hardware interrupt requested when RDRF flag is 1.
4 ILIE	**Idle Line Interrupt Enable (for IDLE)** 0 Hardware interrupts from IDLE disabled (use polling). 1 Hardware interrupt requested when IDLE flag is 1.

	7	6	5	4	3	2	1	0
R	Bit 7	6	5	4	3	2	1	Bit 0
W	Any write to TPMxCNTL clears the 16-bit counter							
Reset	0	0	0	0	0	0	0	0

Figure 15-9. TPM Counter Register Low (TPMxCNTL)

When BDM is active, the timer counter is frozen (this is the value that will be read by user); the coherency mechanism is frozen such that the buffer latches remain in the state they were in when the BDM became active, even if one or both counter halves are read while BDM is active. This assures that if the user was in the middle of reading a 16-bit register when BDM became active, it will read the appropriate value from the other half of the 16-bit value after returning to normal execution.

In BDM mode, writing any value to TPMxSC, TPMxCNTH or TPMxCNTL registers resets the read coherency mechanism of the TPMxCNTH:L registers, regardless of the data involved in the write.

15.3.3 TPM Counter Modulo Registers (TPMxMODH:TPMxMODL)

The read/write TPM modulo registers contain the modulo value for the TPM counter. After the TPM counter reaches the modulo value, the TPM counter resumes counting from 0x0000 at the next clock, and the overflow flag (TOF) becomes set. Writing to TPMxMODH or TPMxMODL inhibits the TOF bit and overflow interrupts until the other byte is written. Reset sets the TPM counter modulo registers to 0x0000 which results in a free running timer counter (modulo disabled).

Writing to either byte (TPMxMODH or TPMxMODL) latches the value into a buffer and the registers are updated with the value of their write buffer according to the value of CLKSB:CLKSA bits, so:

- If (CLKSB:CLKSA = 0:0), then the registers are updated when the second byte is written
- If (CLKSB:CLKSA not = 0:0), then the registers are updated after both bytes were written, and the TPM counter changes from (TPMxMODH:TPMxMODL - 1) to (TPMxMODH:TPMxMODL). If the TPM counter is a free-running counter, the update is made when the TPM counter changes from 0xFFFE to 0xFFFF

The latching mechanism may be manually reset by writing to the TPMxSC address (whether BDM is active or not).

When BDM is active, the coherency mechanism is frozen (unless reset by writing to TPMxSC register) such that the buffer latches remain in the state they were in when the BDM became active, even if one or both halves of the modulo register are written while BDM is active. Any write to the modulo registers bypasses the buffer latches and directly writes to the modulo register while BDM is active.

	7	6	5	4	3	2	1	0
R W	Bit 15	14	13	12	11	10	9	Bit 8
Reset	0	0	0	0	0	0	0	0

Figure 15-10. TPM Counter Modulo Register High (TPMxMODH)

TPM counter changes from (TPMxMODH:L - 1) to (TPMxMODH:L). If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from $FFFE to $FFFF. Instead, the TPM v2 makes this update after that the both bytes were written and when the TPM counter changes from TPMxMODH:L to $0000.

- Center-Aligned PWM (Section 15.4.2.4, “Center-Aligned PWM Mode)

  In this mode and if (CLKSB:CLKSA not = 00), the TPM v3 updates the TPMxCnVH:L registers with the value of their write buffer after that the both bytes were written and when the TPM counter changes from (TPMxMODH:L - 1) to (TPMxMODH:L). If the TPM counter is a free-running counter, then this update is made when the TPM counter changes from $FFFE to $FFFF. Instead, the TPM v2 makes this update after that the both bytes were written and when the TPM counter changes from TPMxMODH:L to (TPMxMODH:L - 1).

5. Center-Aligned PWM (Section 15.4.2.4, “Center-Aligned PWM Mode)
   - TPMxCnVH:L = TPMxMODH:L [SE110-TPM case 1]

     In this case, the TPM v3 produces 100% duty cycle. Instead, the TPM v2 produces 0% duty cycle.
   - TPMxCnVH:L = (TPMxMODH:L - 1) [SE110-TPM case 2]

     In this case, the TPM v3 produces almost 100% duty cycle. Instead, the TPM v2 produces 0% duty cycle.
   - TPMxCnVH:L is changed from 0x0000 to a non-zero value [SE110-TPM case 3 and 5]

     In this case, the TPM v3 waits for the start of a new PWM period to begin using the new duty cycle setting. Instead, the TPM v2 changes the channel output at the middle of the current PWM period (when the count reaches 0x0000).
   - TPMxCnVH:L is changed from a non-zero value to 0x0000 [SE110-TPM case 4]

     In this case, the TPM v3 finishes the current PWM period using the old duty cycle setting. Instead, the TPM v2 finishes the current PWM period using the new duty cycle setting.
6. Write to TPMxMODH:L registers in BDM mode (Section 15.3.3, “TPM Counter Modulo Registers (TPMxMODH:TPMxMODL))

   In the TPM v3 a write to TPMxSC register in BDM mode clears the write coherency mechanism of TPMxMODH:L registers. Instead, in the TPM v2 this coherency mechanism is not cleared when there is a write to TPMxSC register.
7. Update of EPWM signal when CLKSB:CLKSA = 00

   In the TPM v3 if CLKSB:CLKSA = 00, then the EPWM signal in the channel output is not update (it is frozen while CLKSB:CLKSA = 00). Instead, in the TPM v2 the EPWM signal is updated at the next rising edge of bus clock after a write to TPMxCnSC register.

   The Figure 0-1 and Figure 0-2 show when the EPWM signals generated by TPM v2 and TPM v3 after the reset (CLKSB:CLKSA = 00) and if there is a write to TPMxCnSC register.

Table 16-1. BDC Command Summary

Command Mnemonic	Active BDM/ Non-intrusive	Coding Structure	Description
SYNC	Non-intrusive	n/a[1]	Request a timed reference pulse to determine target BDC communication speed
ACK_ENABLE	Non-intrusive	D5/d	Enable acknowledge protocol. Refer to Freescale document order no. HCS08RMv1/D.
ACK_DISABLE	Non-intrusive	D6/d	Disable acknowledge protocol. Refer to Freescale document order no. HCS08RMv1/D.
BACKGROUND	Non-intrusive	90/d	Enter active background mode if enabled (ignore if ENBDM bit equals 0)
READ_STATUS	Non-intrusive	E4/SS	Read BDC status from BDCSCR
WRITE_CONTROL	Non-intrusive	C4/CC	Write BDC controls in BDCSCR
READ_BYTE	Non-intrusive	E0/AAAA/d/RD	Read a byte from target memory
READ_BYTE_WS	Non-intrusive	E1/AAAA/d/SS/RD	Read a byte and report status
READ_LAST	Non-intrusive	E8/SS/RD	Re-read byte from address just read and report status
WRITE_BYTE	Non-intrusive	C0/AAAA/WD/d	Write a byte to target memory
WRITE_BYTE_WS	Non-intrusive	C1/AAAA/WD/d/SS	Write a byte and report status
READ_BKPT	Non-intrusive	E2/RBKP	Read BDCBKPT breakpoint register
WRITE_BKPT	Non-intrusive	C2/WBKP	Write BDCBKPT breakpoint register
GO	Active BDM	08/d	Go to execute the user application program starting at the address currently in the PC
TRACE1	Active BDM	10/d	Trace 1 user instruction at the address in the PC, then return to active background mode
TAGGO	Active BDM	18/d	Same as GO but enable external tagging (HCS08 devices have no external tagging pin)
READ_A	Active BDM	68/d/RD	Read accumulator (A)
READ_CCR	Active BDM	69/d/RD	Read condition code register (CCR)
READ_PC	Active BDM	6B/d/RD16	Read program counter (PC)
READ_HX	Active BDM	6C/d/RD16	Read H and X register pair (H:X)
READ_SP	Active BDM	6F/d/RD16	Read stack pointer (SP)
READ_NEXT	Active BDM	70/d/RD	Increment H:X by one then read memory byte located at H:X
READ_NEXT_WS	Active BDM	71/d/SS/RD	Increment H:X by one then read memory byte located at H:X. Report status and data.
WRITE_A	Active BDM	48/WD/d	Write accumulator (A)
WRITE_CCR	Active BDM	49/WD/d	Write condition code register (CCR)
WRITE_PC	Active BDM	4B/WD16/d	Write program counter (PC)
WRITE_HX	Active BDM	4C/WD16/d	Write H and X register pair (H:X)
WRITE_SP	Active BDM	4F/WD16/d	Write stack pointer (SP)
WRITE_NEXT	Active BDM	50/WD/d	Increment H:X by one, then write memory byte located at H:X
WRITE_NEXT_WS	Active BDM	51/WD/d/SS	Increment H:X by one, then write memory byte located at H:X. Also report status.

[1] The SYNC command is a special operation that does not have a command code.

16.4.3.9 Debug Status Register (DBGS)

This is a read-only status register.

	7	6	5	4	3	2	1	0
R	AF	BF	ARMF	0	CNT3	CNT2	CNT1	CNT0
W	▨	▨	▨	▨	▨	▨	▨	▨
Reset	0	0	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 16-9. Debug Status Register (DBGS)

Table 16-6. DBGS Register Field Descriptions

Field	Description
7 AF	**Trigger Match A Flag** — AF is cleared at the start of a debug run and indicates whether a trigger match A condition was met since arming. 0 Comparator A has not matched 1 Comparator A match
6 BF	**Trigger Match B Flag** — BF is cleared at the start of a debug run and indicates whether a trigger match B condition was met since arming. 0 Comparator B has not matched 1 Comparator B match
5 ARMF	**Arm Flag** — While DBGEN = 1, this status bit is a read-only image of ARM in DBGC. This bit is set by writing 1 to the ARM control bit in DBGC (while DBGEN = 1) and is automatically cleared at the end of a debug run. A debug run is completed when the FIFO is full (begin trace) or when a trigger event is detected (end trace). A debug run can also be ended manually by writing 0 to ARM or DBGEN in DBGC. 0 Debugger not armed 1 Debugger armed
3:0 CNT[3:0]	**FIFO Valid Count** — These bits are cleared at the start of a debug run and indicate the number of words of valid data in the FIFO at the end of a debug run. The value in CNT does not decrement as data is read out of the FIFO. The external debug host is responsible for keeping track of the count as information is read out of the FIFO. 0000 Number of valid words in FIFO = No valid data 0001 Number of valid words in FIFO = 1 0010 Number of valid words in FIFO = 2 0011 Number of valid words in FIFO = 3 0100 Number of valid words in FIFO = 4 0101 Number of valid words in FIFO = 5 0110 Number of valid words in FIFO = 6 0111 Number of valid words in FIFO = 7 1000 Number of valid words in FIFO = 8

Appendix A
Electrical Characteristics

A.1 Introduction

This section contains the most accurate electrical and timing information for the MC9S08DN60 Series of microcontrollers available at the time of publication.

A.2 Parameter Classification

The electrical parameters shown in this supplement are guaranteed by various methods. To give the customer a better understanding the following classification is used and the parameters are tagged accordingly in the tables where appropriate:

Table A-1. Parameter Classifications

P	Those parameters are guaranteed during production testing on each individual device.
C	Those parameters are achieved by the design characterization by measuring a statistically relevant sample size across process variations.
T	Those parameters are achieved by design characterization on a small sample size from typical devices under typical conditions unless otherwise noted. All values shown in the typical column are within this category.
D	Those parameters are derived mainly from simulations.

NOTE

The classification is shown in the column labeled “C” in the parameter tables where appropriate.

A.3 Absolute Maximum Ratings

Absolute maximum ratings are stress ratings only, and functional operation at the maxima is not guaranteed. Stress beyond the limits specified in Table A-2 may affect device reliability or cause permanent damage to the device. For functional operating conditions, refer to the remaining tables in this section.

Table A-12. MCG Frequency Specifications (Temperature Range = –40 to 125°C Ambient) (continued)

Num	C	Rating	Symbol	Min	Typical	Max	Unit
18	T	RMS frequency variation of a single clock cycle measured 625 ns after reference edge.[6]	$f_{pll\_cycjit\_625ns}$	—	0.566[4]	—	$\%f_{pll}$
19	T	Maximum frequency variation averaged over 625 ns window.	$f_{pll\_maxjit\_625ns}$	—	0.113	—	$\%f_{pll}$
20	D	Lock entry frequency tolerance [7]	D_{lock}	± 1.49	—	± 2.98	%
21	D	Lock exit frequency tolerance [8]	D_{unl}	± 4.47	—	± 5.97	%
22	D	Lock time - FLL	t_{fll_lock}	—	—	$t_{fll\_acquire}$+ 1075(1/f_{int_t})	s
23	D	Lock time - PLL	t_{pll_lock}	—	—	$t_{pll\_acquire}$+ 1075(1/f_{pll_ref})	s
24	D	Loss of external clock minimum frequency - RANGE = 0	f_{loc_low}	(3/5) x f_{int}	—	—	kHz
25	D	Loss of external clock minimum frequency - RANGE = 1	f_{loc_high}	(16/5) x f_{int}	—	—	kHz

[1] TRIM register at default value (0x80) and FTRIM control bit at default value (0x0).

[2] This specification applies to any time the FLL reference source or reference divider is changed, trim value changed or changing from FLL disabled (BLPE, BLPI) to FLL enabled (FEI, FEE, FBE, FBI). If a crystal/resonator is being used as the reference, this specification assumes it is already running.

[3] This specification applies to any time the PLL VCO divider or reference divider is changed, or changing from PLL disabled (BLPE, BLPI) to PLL enabled (PBE, PEE). If a crystal/resonator is being used as the reference, this specification assumes it is already running.

[4] Jitter is the average deviation from the programmed frequency measured over the specified interval at maximum f_{BUS}. Measurements are made with the device powered by filtered supplies and clocked by a stable external clock signal. Noise injected into the FLL circuitry via V_{DD} and V_{SS} and variation in crystal oscillator frequency increase the C_{Jitter} percentage for a given interval. Jitter measurements are based upon a 40MHz MCGOUT clock frequency.

[5] In some specifications, this value is described as “long term accuracy of PLL output clock (averaged over 2 ms)” with symbol “$f_{pll\_jitter\_2ms}$.” The parameter is unchanged, but the description has been changed for clarification purposes.

[6] In some specifications, this value is described as “Jitter of PLL output clock measured over 625 ns” with symbol “$f_{pll\_jitter\_625ns}$.” The parameter is unchanged, but the description has been changed for clarification purposes.

[7] Below D_{lock} minimum, the MCG is guaranteed to enter lock. Above D_{lock} maximum, the MCG will not enter lock. But if the MCG is already in lock, then the MCG may stay in lock.

[8] Below D_{unl} minimum, the MCG will not exit lock if already in lock. Above D_{unl} maximum, the MCG is guaranteed to exit lock.